

ABSTRACT OF THE DISCLOSURE

This invention is intended to connect a dummy lead while preventing depression of a resin that seals electric connection sections, without bringing
5 the dummy lead into contact with a recording element substrate or without taking the dummy lead for a lead electrode. The dummy lead which is provided inward of an opening of a flexible film wiring substrate to be shorter than the lead electrode, and which is not
10 electrically connected to an electrode pad is provided to be adjacent to the lead electrode.